



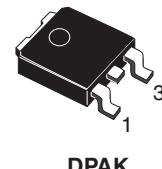
STD35N3LH5

N-channel 30 V, 12.5 mΩ, 35 A, DPAK
STripFET™ V Power MOSFET

Features

Order code	V _{DSS}	R _{DS(on)} max	I _D
STD35N3LH5	30 V	< 16 mΩ	35 A

- 100% avalanche tested
- Surface mounting DPAK (TO-252)
- Low gate drive power losses



DPAK

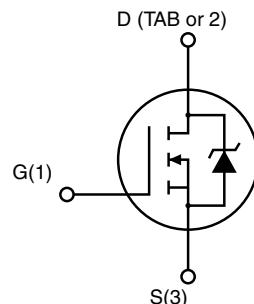
Applications

- Switching applications
 - Automotive

Description

The STD35N3LH5 is a N-channel STripFET™ V. This Power MOSFET technology is among the latest improvements, which have been especially tailored to achieve very low on-state resistance providing also one of the best-in-class figure of merit (FOM).

Figure 1. Internal schematic diagram



AM01474v1

Table 1. Device summary

Order code	Marking	Package	Packaging
STD35N3LH5	D35N3LH5	DPAK	Tape and reel

Contents

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS}=0$)	30	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	35	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	22	A
$I_{DM}^{(2)}$	Drain current (pulsed)	140	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	35	W
T_j T_{stg}	Operating junction temperature Storage temperature	-55 to 175	$^\circ\text{C}$

1. The value is rated according R_{thj-c}
2. Pulse is rated according safe operating area

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	4.3	$^\circ\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-ambient max	50	$^\circ\text{C/W}$

1. When mounted on 1inch² FR-4 2Oz Cu board

Table 4. Avalanche data

Symbol	Parameter	Value	Unit
I_{AV}	Not-repetitive avalanche current	14	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$, $I_D = I_{AV}$, $V_{DD} = 24\text{ V}$)	100	mJ

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 5. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0$	30			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}, V_{GS} = \text{Max rating}, T_c = 125^\circ\text{C}$			1 10	μA μA
I_{GSS}	Gate body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20 \text{ V}$			± 100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1		2.5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		12.5 18	16 20	$\text{m}\Omega$

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min	Typ.	Max.	Unit
C_{iss}	Input capacitance			713		pF
C_{oss}	Output capacitance	$V_{DS} = 27.5 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	135	-	pF
C_{rss}	Reverse transfer capacitance			22		pF
Q_g	Total gate charge			5.4		nC
Q_{gs}	Gate-source charge	$V_{DD} = 15 \text{ V}, I_D = 19 \text{ A}$	-	2	-	nC
Q_{gd}	Gate-drain charge	$V_{GS} = 4.5 \text{ V}$ <i>Figure 14</i>		2.1		nC
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz open drain}$	-	3.3	-	Ω

Table 7. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	$V_{DD}=15\text{ V}$, $I_D=5.5\text{ A}$, $R_G=4.7\Omega$, $V_{GS}=10\text{ V}$ <i>Figure 16</i>	-	4 4	-	ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time		-	20 3.5	-	ns ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)	$I_{SD}=35\text{ A}$, $V_{GS}=0$	-		35 140	A A
$V_{SD}^{(2)}$	Forward on voltage		-		1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD}=11\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD}=24\text{ V}$, $T_j=150\text{ }^\circ\text{C}$ <i>Figure 15</i>	-	20 10.5 1		ns nC A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

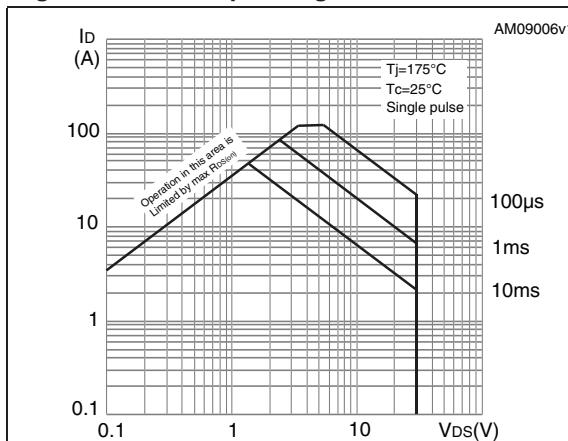


Figure 3. Thermal impedance

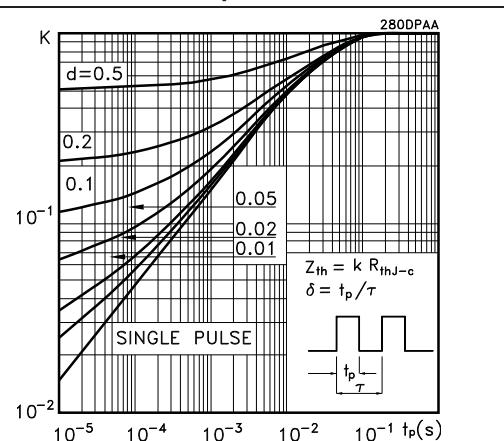


Figure 4. Output characteristics

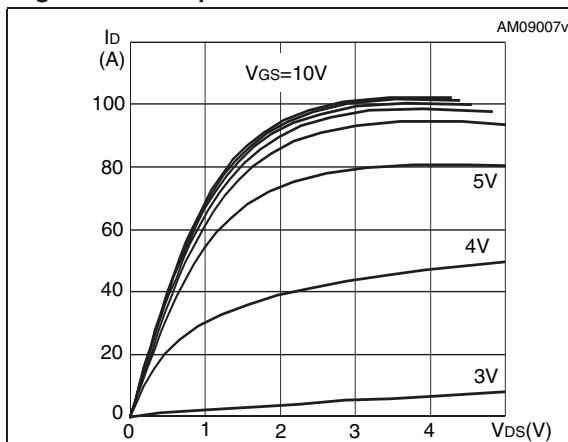


Figure 5. Transfer characteristics

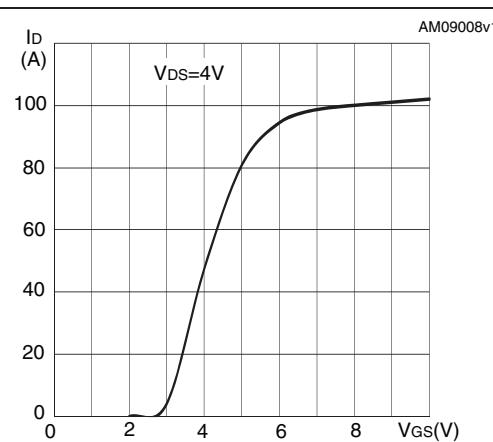
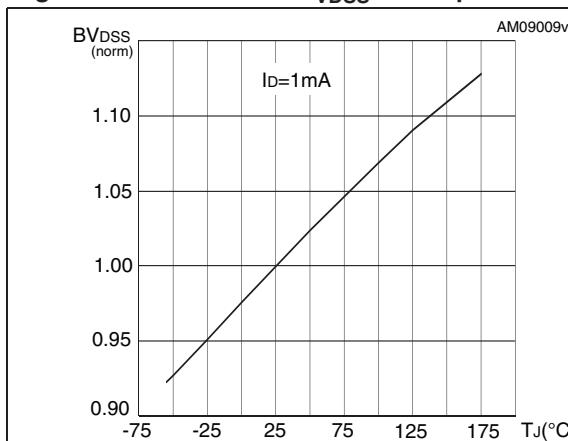
Figure 6. Normalized B_{VDS} vs temperature

Figure 7. Static drain-source on resistance

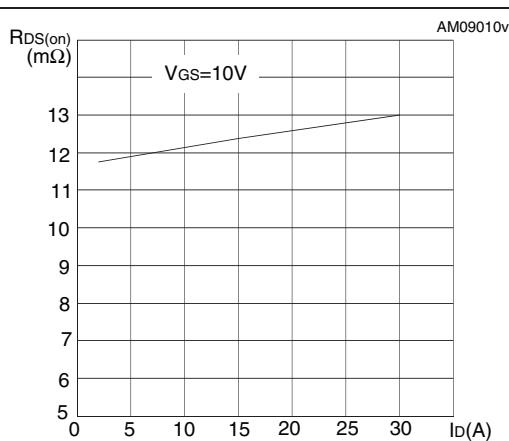
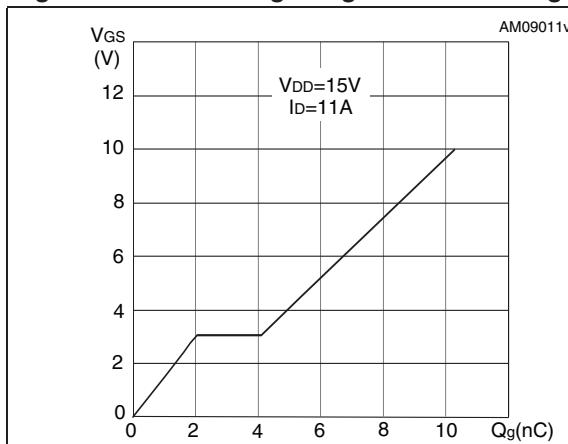
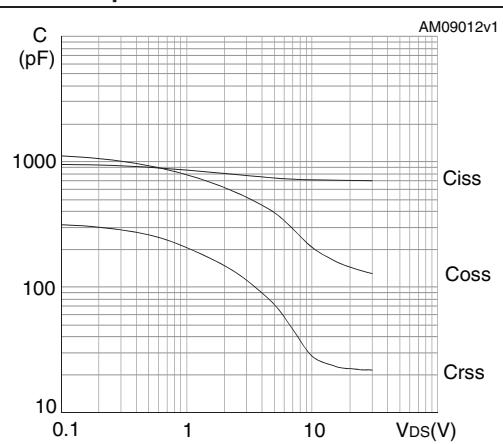
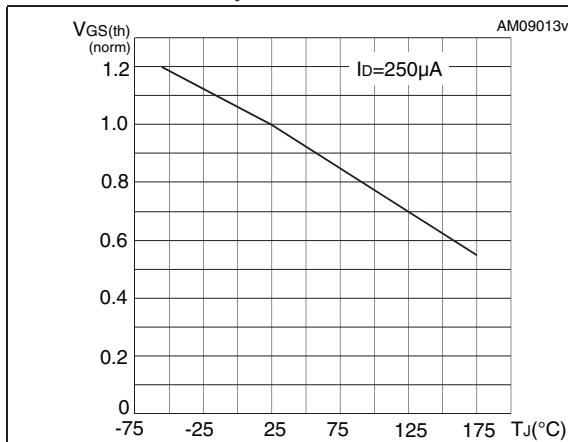
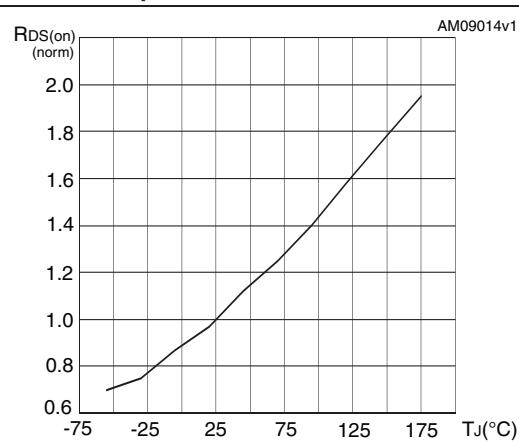
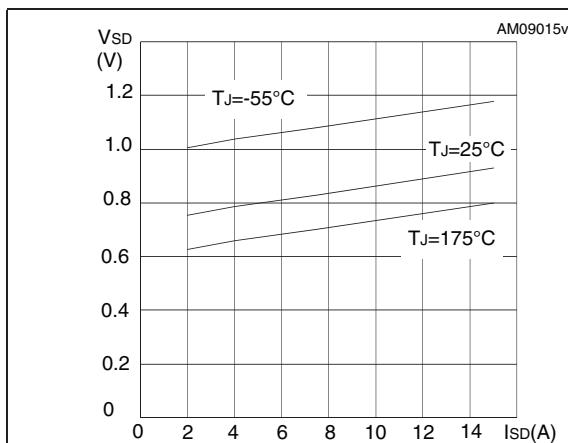


Figure 8. Gate charge vs gate-source voltage**Figure 9. Capacitance variations****Figure 10. Normalized gate threshold voltage vs temperature****Figure 11. Normalized on resistance vs temperature****Figure 12. Source-drain diode forward characteristics**

3 Test circuits

Figure 13. Switching times test circuit for resistive load

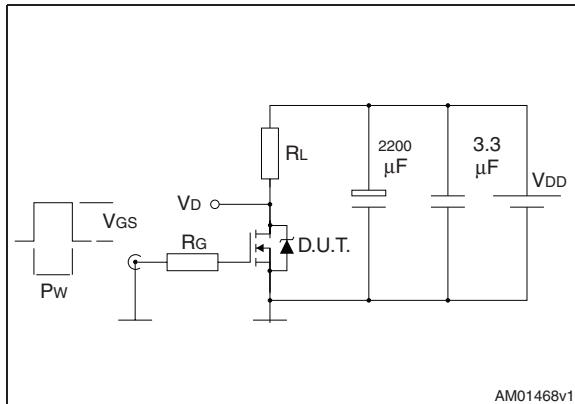


Figure 14. Gate charge test circuit

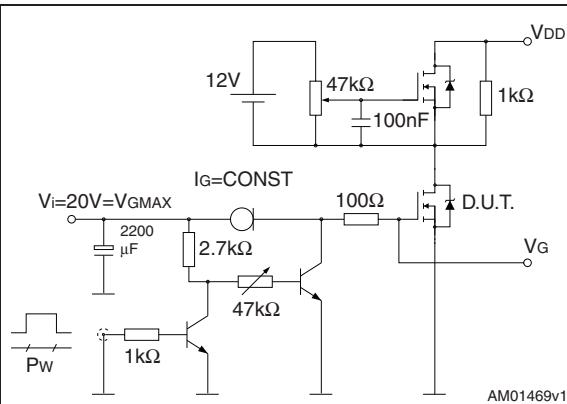


Figure 15. Test circuit for inductive load switching and diode recovery times

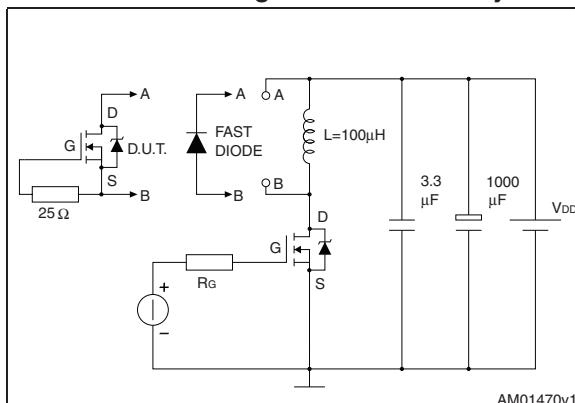


Figure 16. Unclamped inductive load test circuit

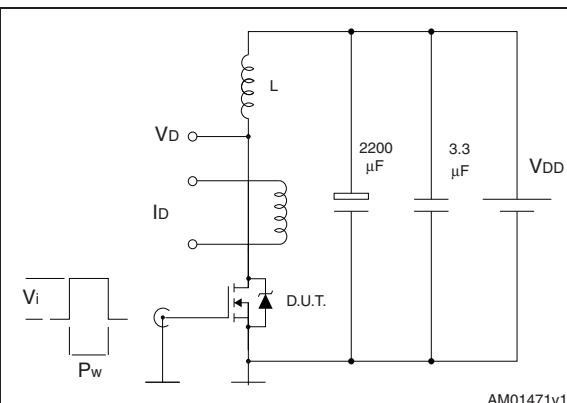


Figure 17. Unclamped inductive waveform

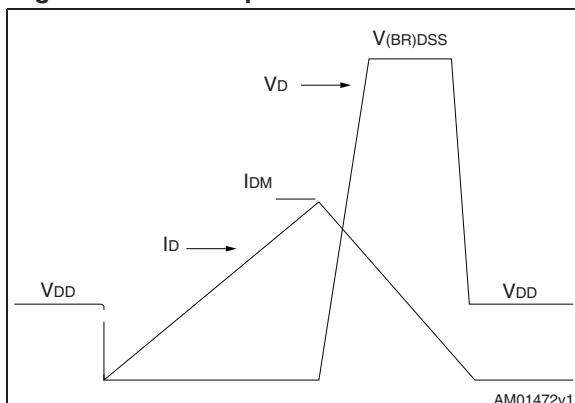
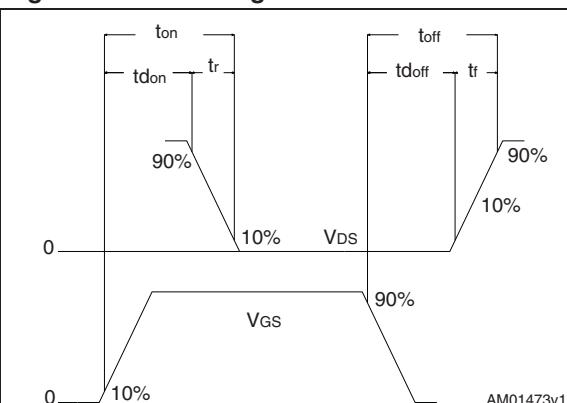


Figure 18. Switching time waveform

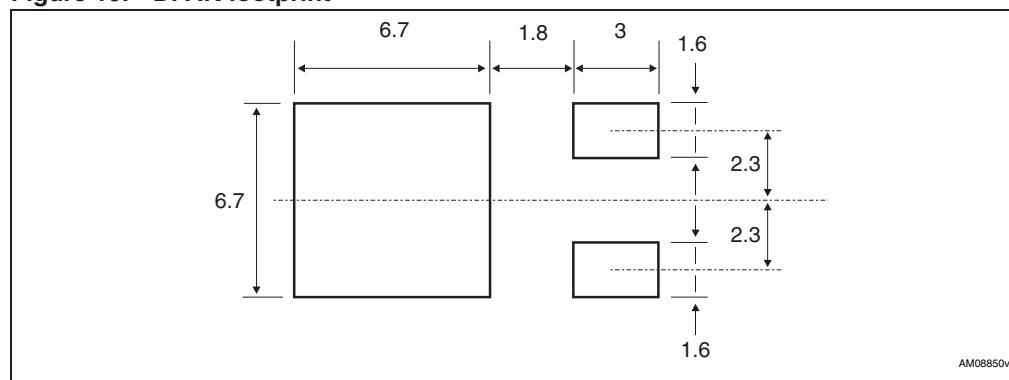


4 Package mechanical data

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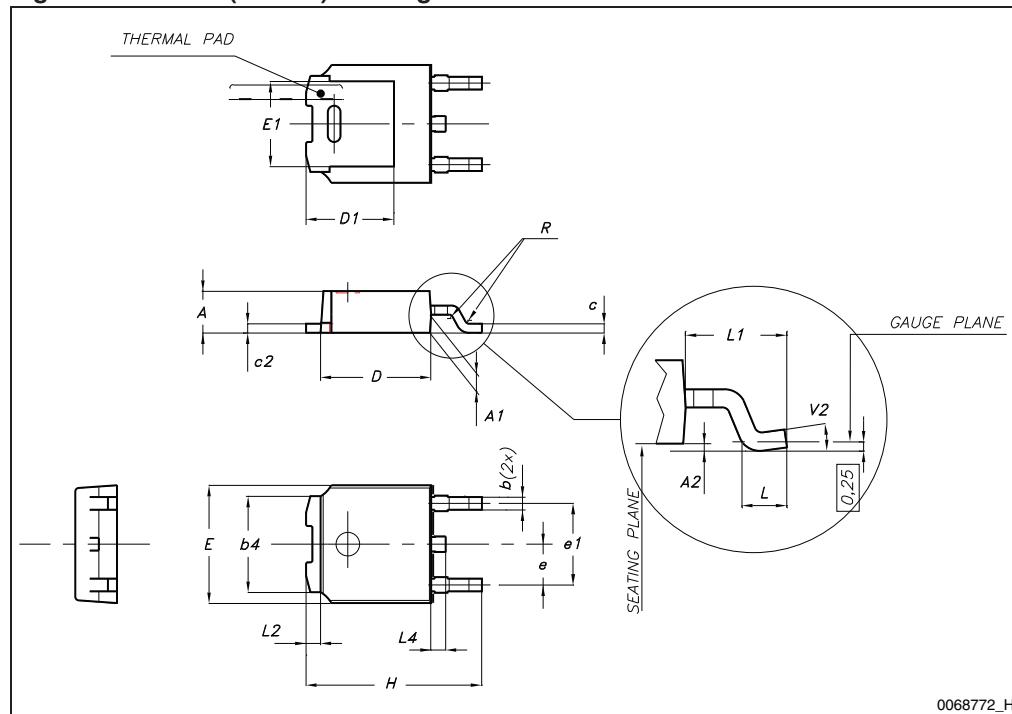
Table 9. DPAK (TO-252) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1		1.50
L1		2.80	
L2		0.80	
L4	0.60		1
R		0.20	
V2	0°		8°

Figure 19. DPAK footprint^(a)

a. All dimension are in millimeters

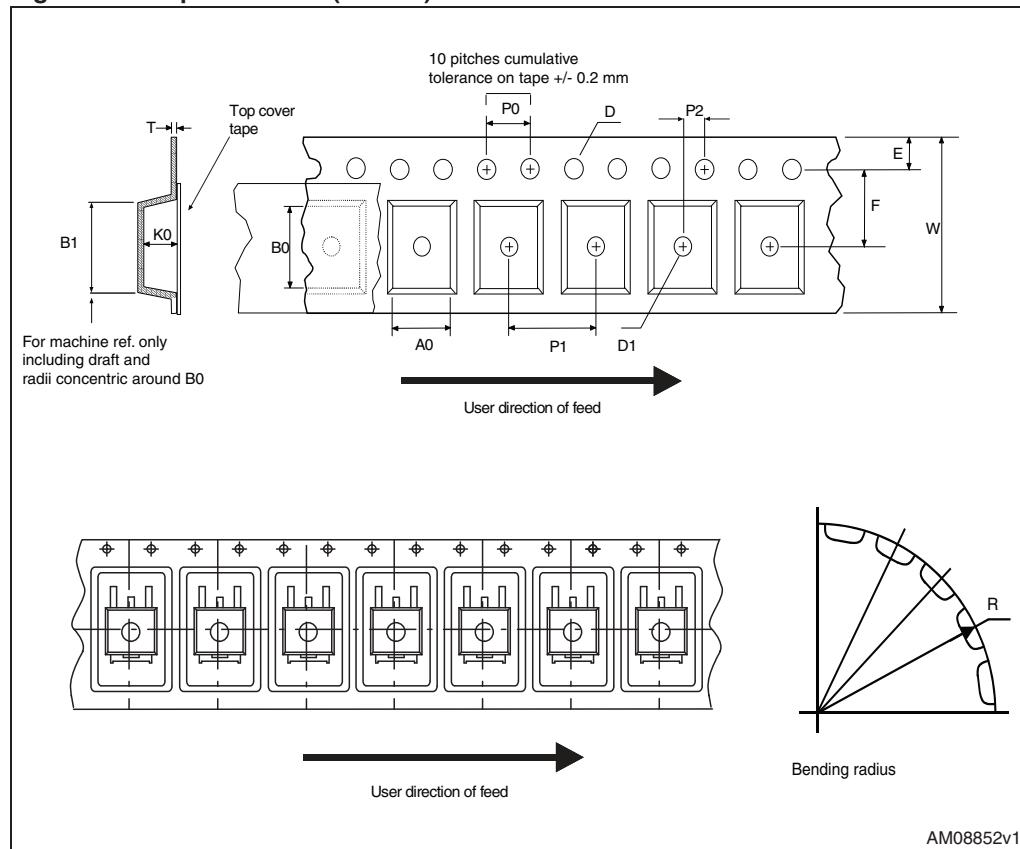
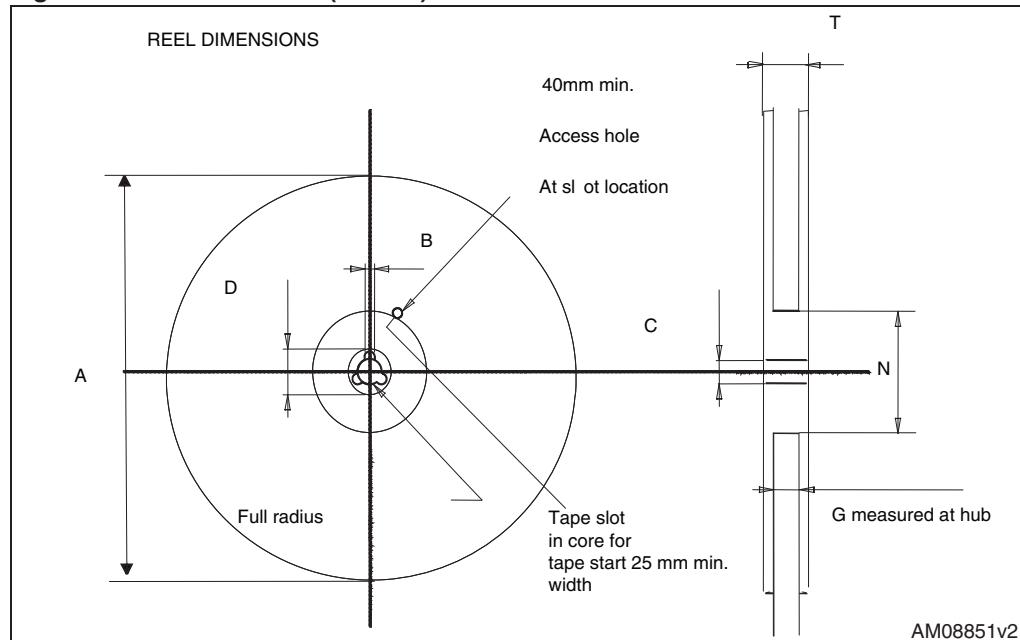
Figure 20. DPAK (TO-252) drawing



5 Packaging mechanical data

Table 10. DPAK (TO-252) tape and reel mechanical data

Dim.	Tape		Reel		
	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Figure 21. Tape for DPAK (TO-252)**Figure 22.** Reel for DPAK (TO-252)

6 Revision history

Table 11. Document revision history

Date	Revision	Changes
02-Oct-2009	1	First release.
18-May-2011	2	Document status promoted from preliminary data to datasheet.

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